

Teledyne DALSA

Our People, Technology, and Products

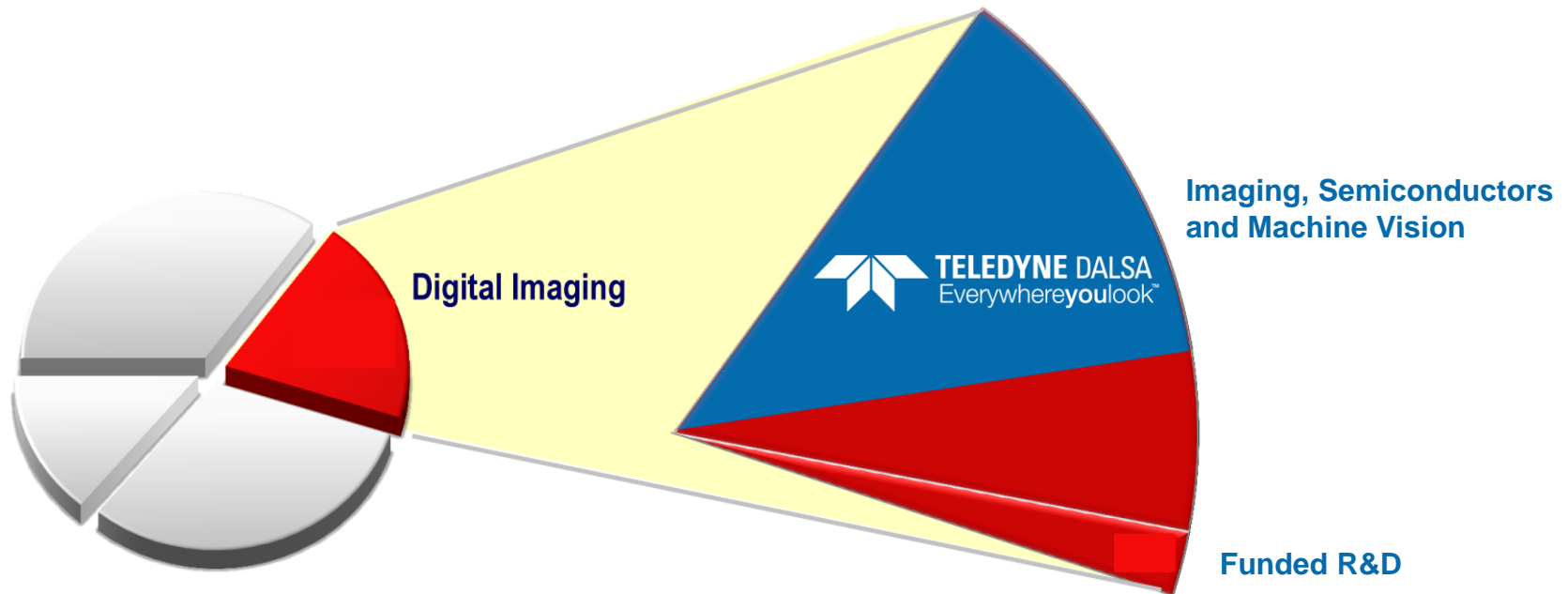


Our Parent Company, Teledyne Technologies

- Teledyne is a US-based leading provider of sophisticated electronic subsystems, instrumentation and communication products, engineered systems, and energy and power generation systems
- Headquarters in Thousand Oaks, CA
- Revenue of \$2.4 billion in 2014



Where We Fit In

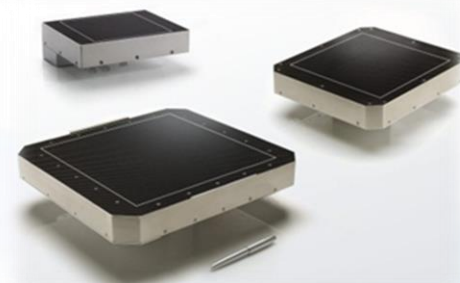
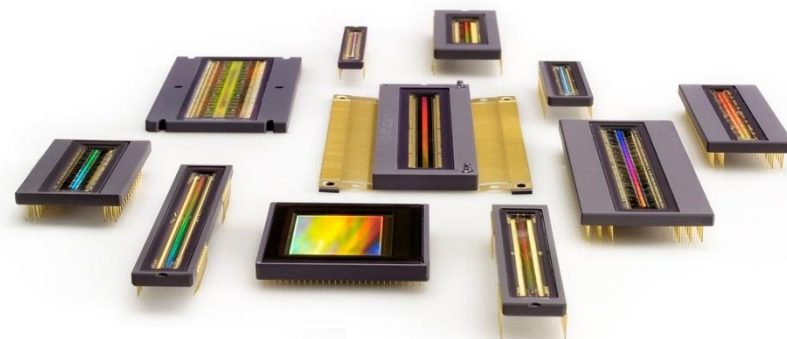


2014 Digital Imaging Segment Overview:

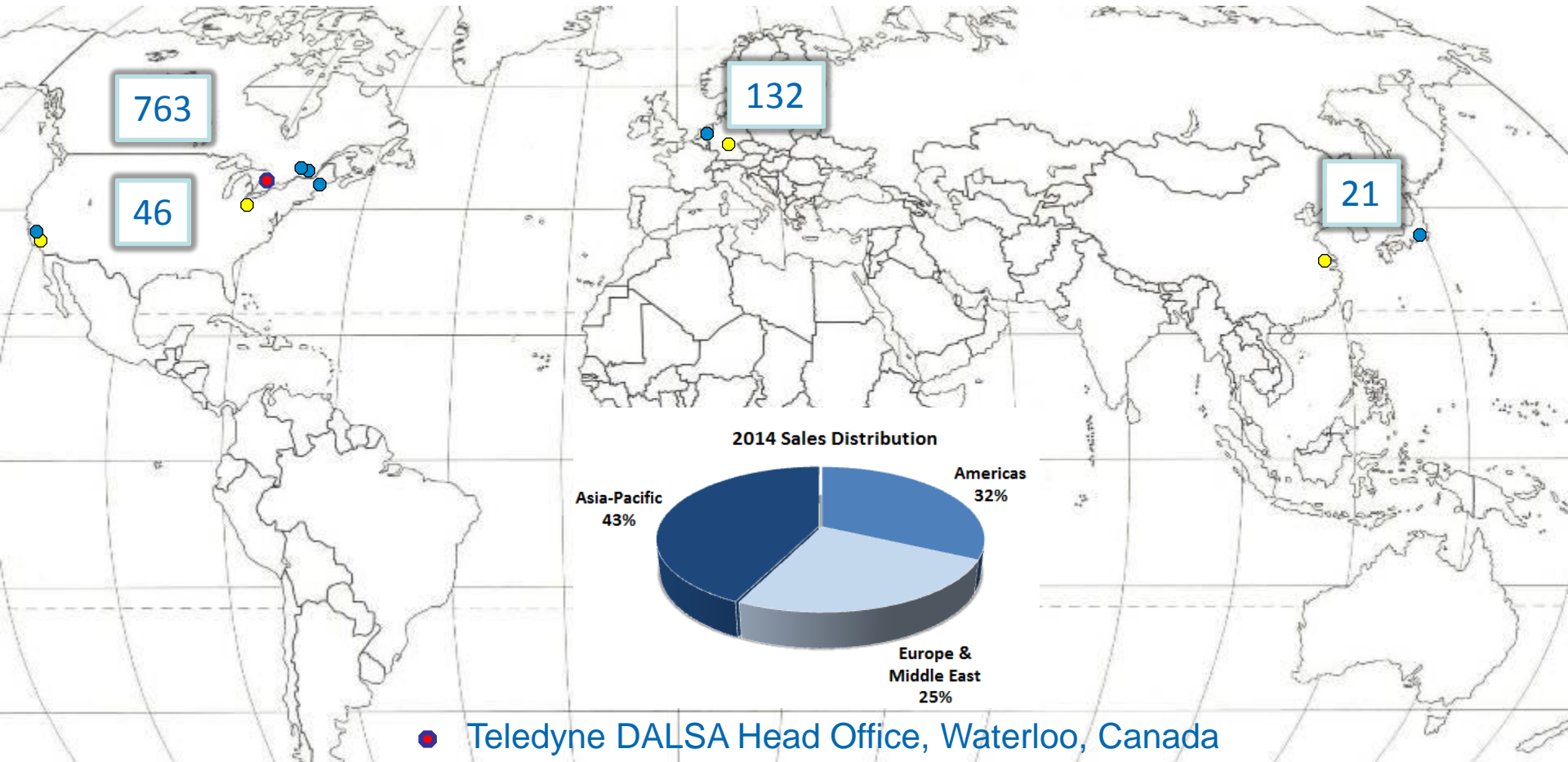
- Sales: \$404M | 16.8% of total

Teledyne DALSA at a Glance

- Provider of high performance digital imaging and semiconductor solutions
- Operations based in Canada, US and Netherlands
- Sales and customer support offices world-wide
- 962 employees world-wide



Worldwide Operations; 97% Exports



- Teledyne DALSA Head Office, Waterloo, Canada
- Teledyne DALSA Operating Locations (Canada, US, NL)
- Teledyne DALSA Sales and Technical Customer Support (Canada, US East, Central, West, Munich, Tokyo, Shanghai)

Two Sides of the Business

Digital Imaging

Leading supplier of high performance digital imaging components



Semiconductor

Leading MEMS wafer foundry
Internal supplier of CCD image sensor wafers



Our Organization

Robert Mehrabian
Chairman, President, and CEO
Teledyne Technologies Incorporated



Rex Geveden
Executive Vice President
Digital Imaging and Engineered Systems
President
Teledyne DALSA



Aldo (Al) Pichelli
Executive Vice President
Instrumentation and Aerospace and Defense Electronics



Human Resources
Information Systems and Technology

Semiconductor Foundry Services
Claude Jean
Executive VP and GM
(Bromont)



Professional Imaging
Guido Aelbers
Executive VP and GM
(Eindhoven)



Asia Pacific
Keith Reuben
Executive VP – Sales
Imaging products



Digital Imaging
Gareth Ingram
Executive VP and GM
(Waterloo)



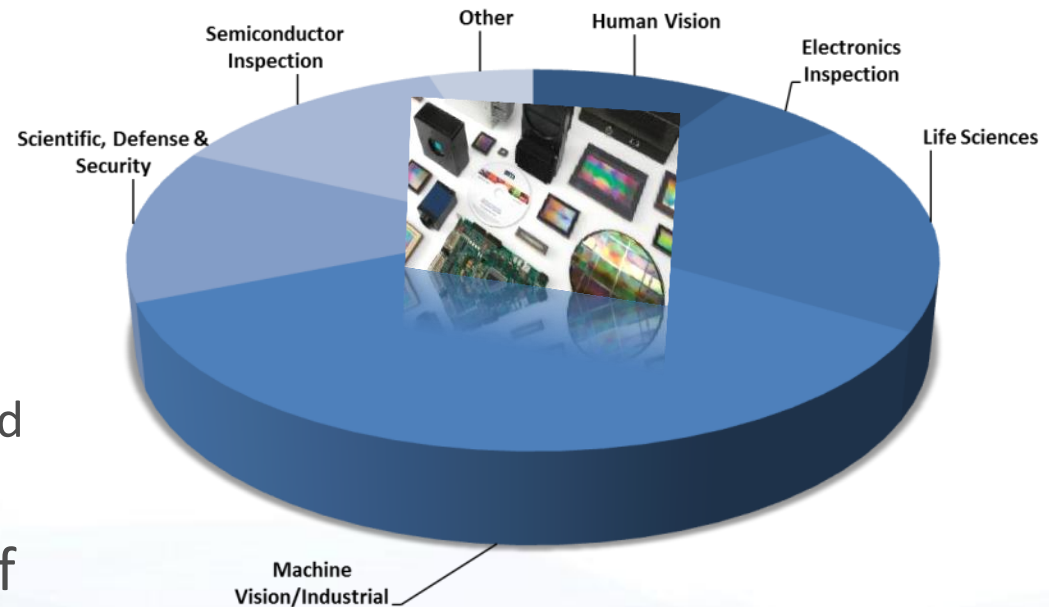
Corporate Finance
Silvio Favrin
Executive VP Finance



Our Digital Imaging Business

- Teledyne DALSA supplies digital imaging components for diverse applications
 - Machine vision / industrial inspection
 - Life sciences
 - Human Vision
 - Space imaging / Defense and Security
- We are a majority owner of Optech, a Canadian leader of LIDAR based imaging systems

Breakdown of Digital Imaging Revenue By End Market Application



We are a Vertically Integrated Supplier

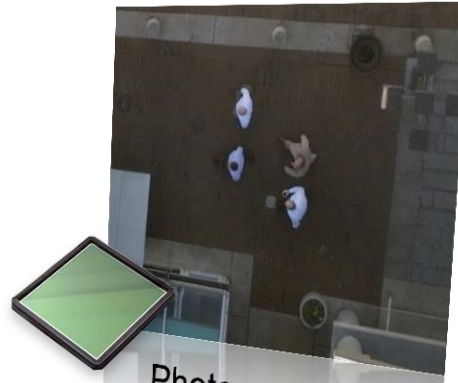
- We are the digital imaging industry's only completely vertically integrated supplier, offering "Silicon to Smart Cameras"



Examples of our Technology at Work



Flat panel inspection



Photogrammetry



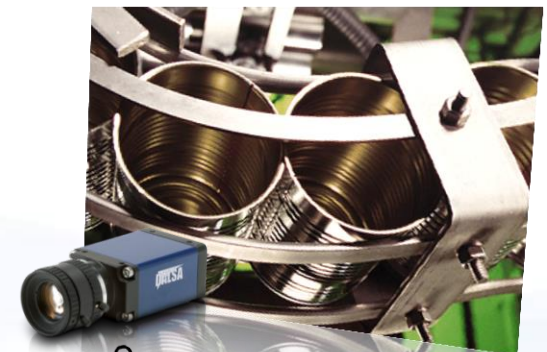
Postal/parcel inspection



Space imaging



Medical x-ray imaging



General machine vision

Our Semiconductor Business

- Specialized semiconductor wafer manufacturer
 - One of the world's leading MEMS foundries
 - A strategic supply of CCD semiconductor wafers and advanced WLP capability to the rest of Teledyne DALSA's business



TELEDYNE DALSA SEMICONDUCTOR FOUNDRY HISTORY

1976 – 2002

Fab run by MITEC to manufacture its telecommunication CMOS chips on 75mm-100mm-150mm

2002

Fab acquired by DALSA to manufacture CCD image sensors as well as start doing MEMS foundry

2004

Fab4 (12,000 sq ft expansion for 150mm MEMS wafers) along with CCD BST facility built

2009

200mm MEMS wafer expansion

2011

Acquisition of DALSA by Teledyne Technologies

2012

Collaborative Center for MiQro Innovation (C2MI) start of operation – Achieved top pure play MEMS foundry

2014

Exceeded \$40M MEMS sales for the first time



TELEDYNE DALSA SEMICONDUCTOR ORGANIZATION



Claude Jean
Executive VP & GM



Luc Ouellet
VP manuf tech
dev



Marc
Faucher
Dir product
solution



Stéphane
Blain
Dir of
operations



Claude Jean
Acting Dir
quality-
environment



Donald
Robert
VP sales &
marketing



Judith
Brunelle
Dir HR



Julie
Morneau
Dir finance



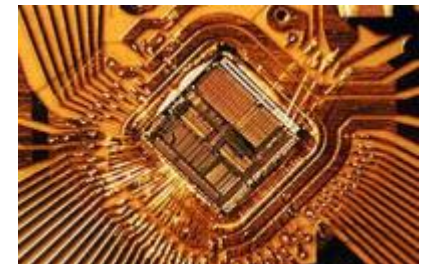
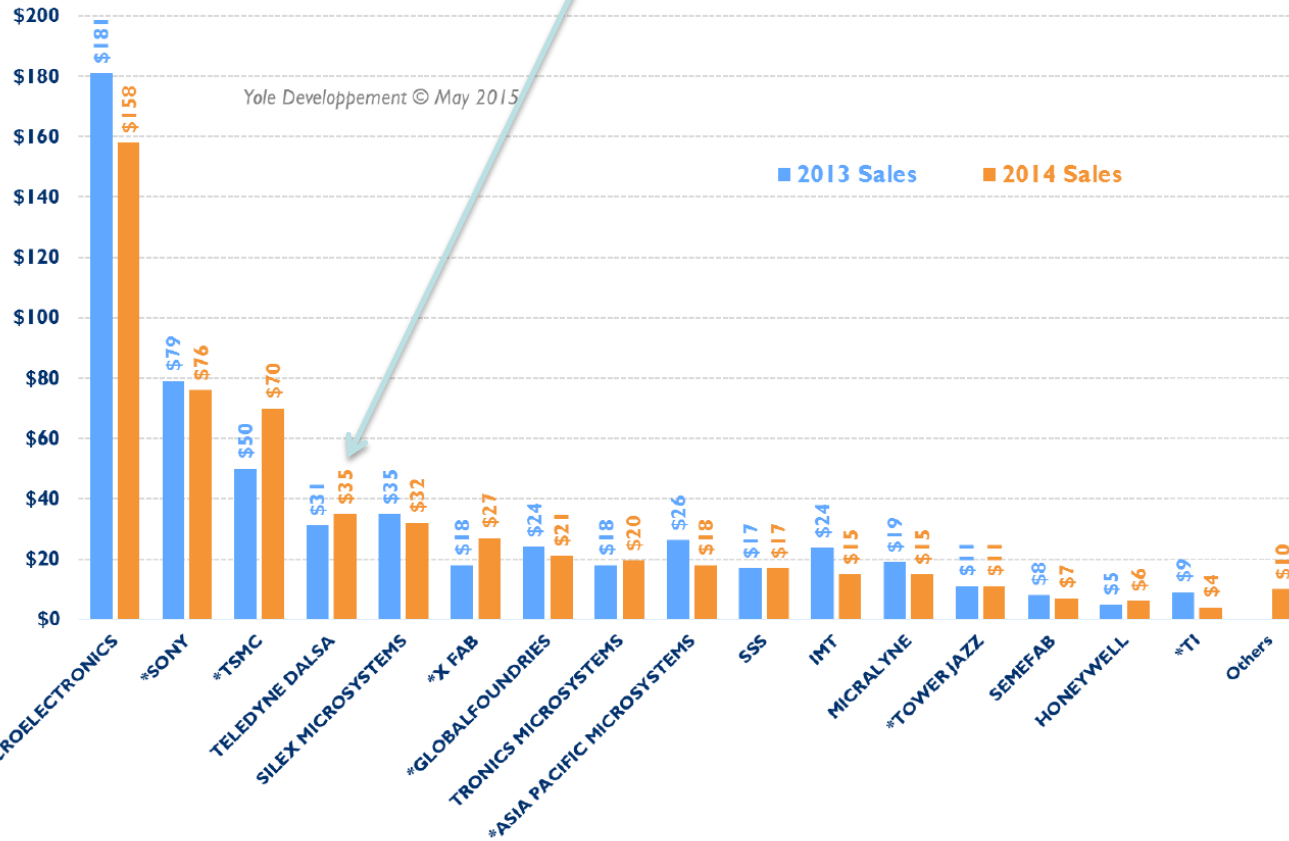
TELEDYNE DALSA
Everywhereyoulook™

TELEDYNE DALSA SEMICONDUCTOR A LEADING PURE PLAY MEMS FOUNDRY

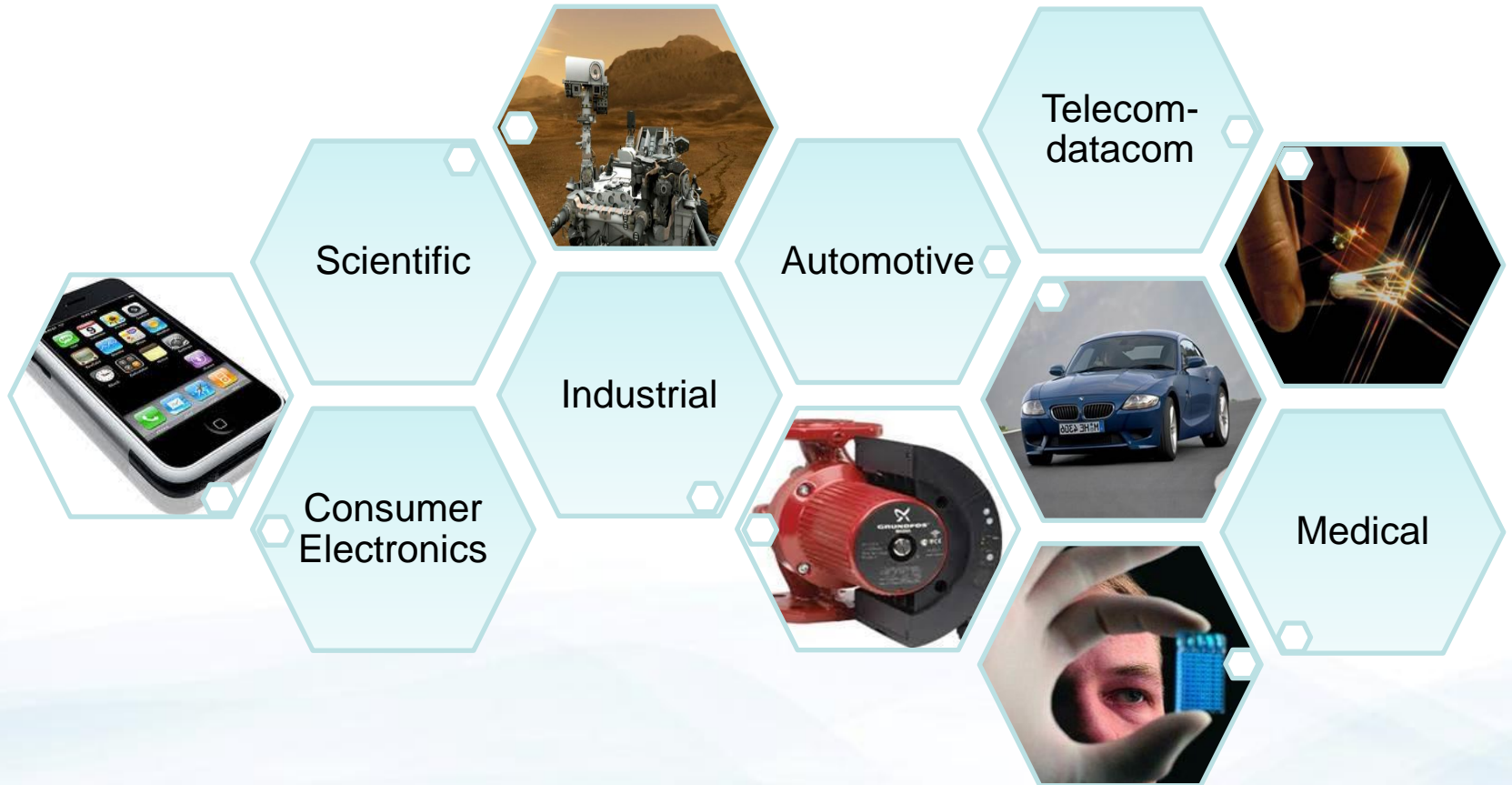
2014 TOP MEMS Foundries (revenue in \$M)

Only the MEMS foundry business is taken into account - *Players can also perform ASIC foundry which is not counted here

Yole Developpement © May 2015

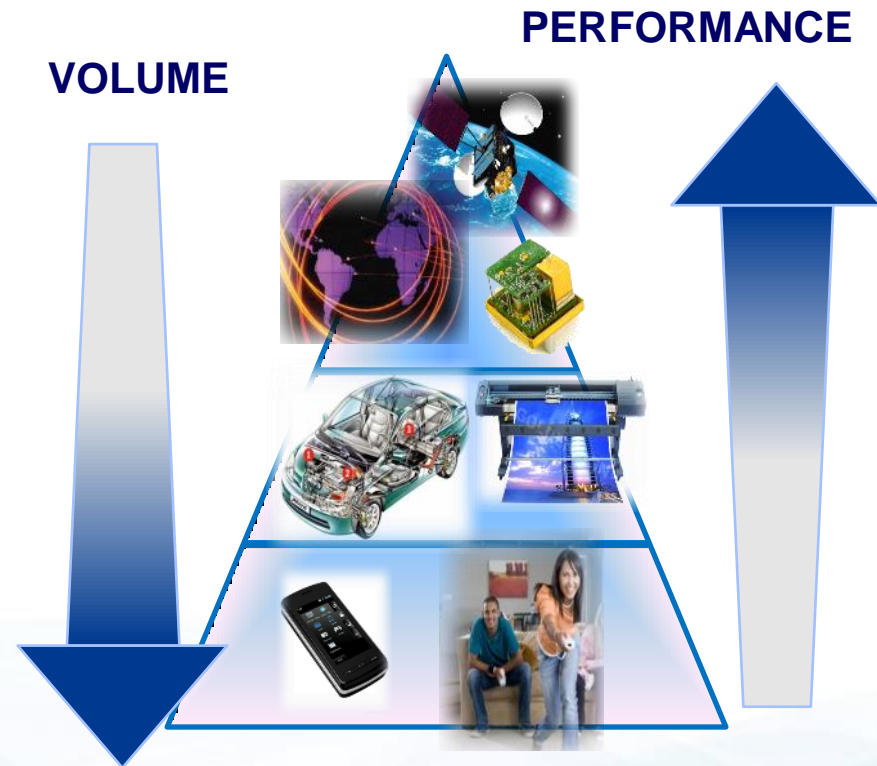


TELEDYNE DALSA SEMICONDUCTOR MEMS and CCD sensors are Everywhere You Look !



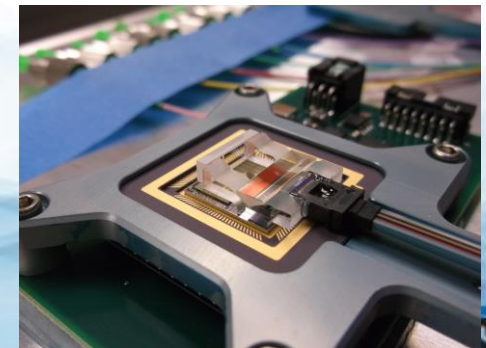
TELEDYNE DALSA SEMICONDUCTOR FOUNDRY BUSINESS MODEL

- Combine in the same fab consumer/automotive high volume products + industrial/scientific/medical high value added products
 - High volumes products require an expensive, high throughput set of equipment but can provide the margins to fully pay for it
 - High value added products need performance that usually comes with an expensive and highly automated set of equipment but cannot pay for it by itself
 - Both combined = model that works



Typical applications & markets served

- Microphones for consumer products
- Pressure, flow and Temp sensors for industrial products
- Pressure sensors for automotive
- Micromirrors for fiber optic switching
- BioMEMS for research
- Nozzle plates for industrial printers





Engagement model

1. If customer is looking to transfer to TDSI an existing MEMS, then 2 options:

- a) Copy exact of the process flow in TDSI fab to implement customer design.
- b) Adaptation of the process flow with TDSI technologies to implement customer design as is or with some design modifications.

Both options a) or b) can be done on 150mm or 200mm depending on volumes and technologies. Some process steps can be done at C2MI if not available at TDSI

Engagement model

2. If customer is looking at developing a new MEMS process and design with TDSI:

a) Customer have capability to design the MEMS ?

YES: joint design and process flow development between customer and TDSI. TDSI provide design assistance, simulation and modelisation services, DRC, etc...

NO: Customer/TDSI need to identify a design partner

b) High volume application ?

YES: Process flow developed in C2MI on 200mm. Process qualification, customer sampling and low volume production can be done in C2MI. TDSI transfer the process flow in its fab when volumes justify the investment

NO: Process flow can be developed on TDSI 150mm line. If required technologies are not available on TDSI 150mm, PF can be developed in C2MI and remain at C2MI for the whole product lifetime if volumes remain low.

In any engagement model, collaboration is always key. MEMS development require close collaboration between all partners

TDSI QUALITY SYSTEM

- TS16949 & ISO14001 Registered
- Qualified automotive supplier; audited by major auto makers in recent years
- Reliability testing and monitoring
- Reverse engineering and failure analysis services
- End-to-end traceability
- Quality System for medical implantable devices – traceability to wafer level / data logging and storage for 25 years
- RoHS compliant
- Root Cause Analysis through 8D





LET US BUILD YOUR SENSORS !

